TEXAS INSTRUMENTS

LM139, LM239, LM339, LM139A
LM239A, LM339A, LM2901, LM2901AV, LM2901V

SLCS006T – OCTOBER 1979 – REVISED JUNE 2015

LMx39x, LM2901xx Quad Differential Comparators

1 Features

- Wide Supply Ranges
  - Single Supply: 2 V to 36 V (Tested to 30 V for Non-V Devices and 32 V for V-Suffix Devices)
  - Dual Supplies: ±1 V to ±18 V (Tested to ±15 V for Non-V Devices and ±16 V for V-Suffix Devices)
- Low Supply-Current Drain Independent of Supply Voltage: 0.8 mA (Typical)
- Low Input Bias Current: 25 nA (Typical)
- Low Input Offset Current: 3 nA (Typical) (LM139)
- Low Input Offset Voltage: 2 mV (Typical)
- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage: ±36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS
- On Products Compliant to MIL-PRF-38535, All Parameters Are Tested Unless Otherwise Noted. On All Other Products, Production Processing Does Not Necessarily Include Testing of All Parameters.

2 Applications

- Industrial
- Automotive
  - HEV/EV and Power Trains
  - Infotainment and Clusters
  - Body Control Modules
- Power Supervision
- Oscillators
- Peak Detectors
- Logic Voltage Translation

3 Description

The LMx39x and the LM2901xx devices consist of four independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible, as long as the difference between the two supplies is 2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

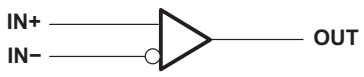
The LM139 and LM139A devices are characterized for operation over the full military temperature range of –55°C to 125°C. The LM239 and LM239A devices are characterized for operation from –25°C to 125°C. The LM339 and LM339A devices are characterized for operation from 0°C to 70°C. The LM2901, LM2901AV, and LM2901V devices are characterized for operation from –40°C to 125°C.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM139x	CDIP (14)	21.30 mm × 7.60 mm
	LCCC (20)	8.90 mm × 8.90 mm
	CFP (14)	9.20 mm × 6.29 mm
LM139x, LM239x, LM339x, LM2901x	SOIC (14)	8.70 mm × 3.90 mm
LM239, LM339x, LM2901	PDIP (14)	19.30 mm × 6.40 mm
LM239, LM2901	TSSOP (14)	5.00 mm × 4.40 mm
LM339x, LM2901	SO (14)	10.20 mm × 5.30 mm
LM339x	SSOP (14)	6.50 mm × 5.30 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Schematic



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

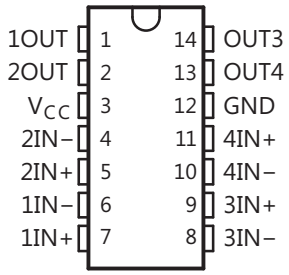
Changes from Revision S (August 2012) to Revision T	Page
• Deleted *Ordering Information* table.	1
• Added Military Disclaimer to *Features* list.	1
• Added *Applications*, *Device Information* table, *Pin Configuration and Functions* section, *ESD Ratings* table, *Thermal Information* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section. No specification changes.	1

5 Device Comparison Table

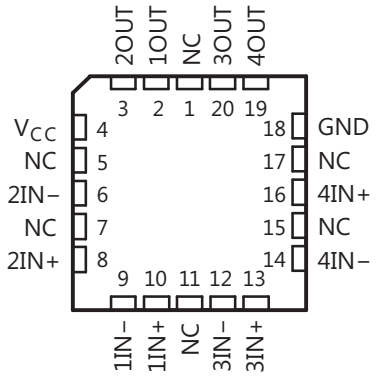
PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM139J, LM139AJ	CDIP (14)	21.30 mm × 7.60 mm
LM139FK, LM139AFK	LCCC (20)	8.90 mm × 8.90 mm
LM139W, LM139AW	CFP (14)	9.20 mm × 6.29 mm
LM139D, LM139AD, LM239D, LM293AD, LM339D, LM339AD, LM2901D	SOIC (14)	8.70 mm × 3.90 mm
LM239N, LM339N, LM339AN, LM2901N	PDIP (14)	19.30 mm × 6.40 mm
LM239PW, LM2901PW	TSSOP (14)	5.00 mm × 4.40 mm
LM339NS, LM339ANS, LM2901NS	SOP (14)	10.20 mm × 5.30 mm
LM339DB, LM339ADB	SSOP (14)	6.50 mm × 5.30 mm

6 Pin Configuration and Functions

D, DB, N, NS, PW, J, or W Package
SOIC, SSOP, PDIP, SO, TSSOP, CDIP, or CFP
Top View



FK Package
20-Pin LCCC(1)
Top View



(1) NC = no internal connection.

Pin Functions

PIN			I/O(1)	DESCRIPTION
NAME	D, J, W, B, PW, DB, N, NS	FK		
1IN+	7	10	I	Positive input pin of the comparator 1
1IN–	6	9	I	Negative input pin of the comparator 1
1OUT	1	2	O	Output pin of the comparator 1
2IN+	5	8	I	Positive input pin of the comparator 2
2IN–	4	6	I	Negative input pin of the comparator 2
2OUT	2	3	O	Output pin of the comparator 2
3IN+	9	13	I	Positive input pin of the comparator 3
3IN–	8	12	I	Negative input pin of the comparator 3
3OUT	14	20	O	Output pin of the comparator 3
4IN+	11	16	I	Positive input pin of the comparator 4
4IN–	10	14	I	Negative input pin of the comparator 4
4OUT	13	19	O	Output pin of the comparator 4
GND	12	18	I	Ground
V_{CC}	3	4	I	Supply pin
NC	—	1	—	No connect (no internal connection)
		5		
		7		
		11		
		15		
		17		

(1) I = Input, O = Output

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage(2)			36	V
V_{ID}	Differential input voltage(3)			±36	V
V_I	Input voltage range (either input)		–0.3	36	V
V_O	Output voltage			36	V
I_O	Output current			20	mA
	Duration of output short circuit to ground(4)		Unlimited		
T_J	Operating virtual-junction temperature			150	°C
	Case temperature for 60 s	FK package		260	°C
	Lead temperature 1.6 mm (1/16 in) from case for 60 s	J package		300	°C
T_{stg}	Storage temperature		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential voltages, are with respect to network ground.
(3) Differential voltages are at xIN+ with respect to xIN–.
(4) Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.

7.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±500	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±750	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage	Non-V devices	2	30	V
		V devices	2	32	V
T_J	Junction temperature		–40	125	°C

7.4 Thermal Information (14-Pin Packages)

THERMAL METRIC(1)		LMx39, LM2901							UNIT
		D (SOIC)	DB (SSOP)	N (PDIP)	NS (SO)	PW (TSSOP)	J (CDIP)	W (CFP)	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	86	96	80	76	113			°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance						15.05	14.65	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, SPRA953.

7.5 Thermal Information (20-Pin Packages)

THERMAL METRIC(1)		LMx39, LM2901	UNIT
		FK (LCCC)	
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	5.61	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, SPRA953.

7.6 Electrical Characteristics for LM139 and LM139A

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS(1)		T_A(2)	LM139			LM139A			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_{CC} = 5 V to 30 V, V_{IC} = V_{ICR} min, V_O = 1.4 V		25°C		2	5		1	2	mV
				Full range			9			4	
I_{IO}	Input offset current	V_O = 1.4 V		25°C		3	25		3	25	nA
				Full range			100			100	
I_{IB}	Input bias current	V_O = 1.4 V		25°C		–25	–100		–25	–100	nA
				Full range			–300			–300	
V_{ICR}	Common-mode input-voltage range(3)			25°C	0 to V_{CC} – 1.5			0 to V_{CC} – 1.5			V
				Full range	0 to V_{CC} – 2			0 to V_{CC} – 2			
A_{VD}	Large-signal differential-voltage amplification	V_{CC+} = ±7.5 V, V_O = –5 V to 5 V		25°C		200		50	200		V/mV
I_{OH}	High-level output current	V_{ID} = 1 V	V_{OH} = 5 V	25°C		0.1			0.1		nA
			V_{OH} = 30 V	Full range			1			1	µA
V_{OL}	Low-level output voltage	V_{ID} = –1 V,	I_{OL} = 4 mA	25°C		150	400		150	400	mV
				Full range			700			700	
I_{OL}	Low-level output current	V_{ID} = –1 V,	V_{OL} = 1.5 V	25°C	6	16		6	16		mA
I_{CC}	Supply current (four comparators)	V_O = 2.5 V,	No load	25°C		0.8	2		0.8	2	mA

(1) All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
(2) Full range (MIN to MAX) for LM139 and LM139A is –55°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
(3) The voltage at either input or common-mode must not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V; however, one input can exceed V_{CC}, and the comparator will provide a proper output state as long as the other input remains in the common-mode range. Either or both inputs can go to 30 V without damage.

7.7 Electrical Characteristics for LMx39 and LMx39A

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS(1)	T_A(2)	LM239 LM339			LM239A LM339A			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_{CC} = 5 V to 30 V, V_{IC} = V_{ICR} min, V_O = 1.4 V	25°C		2	5		1	3	mV
			Full range			9			4	
I_{IO}	Input offset current	V_O = 1.4 V	25°C		5	50		5	50	nA
			Full range			150			150	
I_{IB}	Input bias current	V_O = 1.4 V	25°C		–25	–250		–25	–250	nA
			Full range			–400			–400	
V_{ICR}	Common-mode input-voltage range(3)		25°C	0 to V_{CC} – 1.5			0 to V_{CC} – 1.5			V
			Full range	0 to V_{CC} – 2			0 to V_{CC} – 2			
A_{VD}	Large-signal differential-voltage amplification	V_{CC} = 15 V, V_O = 1.4 V to 11.4 V, R_L ≥ 15 kΩ to V_{CC}	25°C	50	200		50	200		V/mV

(1) All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
(2) Full range (MIN to MAX) for LM239/LM239A is –25°C to 85°C, and for LM339/LM339A is 0°C to 70°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
(3) The voltage at either input or common-mode must not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V; however, one input can exceed V_{CC}, and the comparator will provide a proper output state as long as the other input remains in the common-mode range. Either or both inputs can go to 30 V without damage.

Electrical Characteristics for LMx39 and LMx39A (continued)

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS(1)		T_A(2)	LM239 LM339			LM239A LM339A			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
I_{OH}	High-level output current	V_{ID} = 1 V	V_{OH} = 5 V	25°C		0.1	50		0.1	50	nA
			V_{OH} = 30 V	Full range			1			1	µA
V_{OL}	Low-level output voltage	V_{ID} = –1 V,	I_{OL} = 4 mA	25°C		150	400		150	400	mV
				Full range			700			700	
I_{OL}	Low-level output current	V_{ID} = –1 V,	V_{OL} = 1.5 V	25°C	6	16		6	16		mA
I_{CC}	Supply current (four comparators)	V_O = 2.5 V,	No load	25°C		0.8	2		0.8	2	mA

7.8 Electrical Characteristics for LM2901

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS(1)		T_A(2)	LM2901			UNIT
					MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_{IC} = V_{ICR} min, V_O = 1.4 V, V_{CC} = 5 V to MAX(3)	Non-A devices	25°C		2	7	mV
				Full range			15	
			A-suffix devices	25°C		1	2	
				Full range			4	
I_{IO}	Input offset current	V_O = 1.4 V		25°C		5	50	nA
				Full range			200	
I_{IB}	Input bias current	V_O = 1.4 V		25°C		–25	–250	nA
				Full range			–500	
V_{ICR}	Common-mode input-voltage range(4)			25°C	0 to V_{CC} – 1.5			V
				Full range	0 to V_{CC} – 2			
A_{VD}	Large-signal differential-voltage amplification	V_{CC} = 15 V, V_O = 1.4 V to 11.4 V, R_L ≥ 15 kΩ to V_{CC}		25°C	25	100		V/mV
I_{OH}	High-level output current	V_{ID} = 1 V	V_{OH} = 5 V	25°C		0.1	50	nA
			V_{OH} = V_{CC} MAX(3)	Full range			1	µA
V_{OL}	Low-level output voltage	V_{ID} = –1 V, I_{OL} = 4 mA	Non-V devices	25°C		150	500	mV
			V-suffix devices			150	400	
			All devices	Full range			700	
I_{OL}	Low-level output current	V_{ID} = –1 V,	V_{OL} = 1.5 V	25°C	6	16		mA
I_{CC}	Supply current (four comparators)	V_O = 2.5 V, No load	V_{CC} = 5 V	25°C		0.8	2	mA
			V_{CC} = MAX(3)			1	2.5	

(1) All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
(2) Full range (MIN to MAX) for LM2901 is –40°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
(3) V_{CC} MAX = 30 V for non-V devices, and 32 V for V-suffix devices
(4) The voltage at either input or common-mode must not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V; however, one input can exceed V_{CC}, and the comparator will provide a proper output state as long as the other input remains in the common-mode range. Either or both inputs can go to V_{CC} MAX without damage.

7.9 Switching Characteristics for LM2901

V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS		LM2901	UNIT
			TYP	
Response time	R_L connected to 5 V through 5.1 kΩ, C_L = 15 pF(1)(2)	100-mV input step with 5-mV overdrive	1.3	µs
		TTL-level input step	0.3	

(1) C_L includes probe and jig capacitance.
(2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

7.10 Switching Characteristics for LM139 and LM139A

V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS		LM139 LM139A	UNIT
			TYP	
Response time	R_L connected to 5 V through 5.1 kΩ, C_L = 15 pF(1)(2)	100-mV input step with 5-mV overdrive	1.3	µs
		TTL-level input step	0.3	

(1) C_L includes probe and jig capacitance.
(2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

7.11 Switching Characteristics for LMx39 and LMx39A

V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS		LM239 LM239A LM339 LM339A	UNIT
			TYP	
Response time	R_L connected to 5 V through 5.1 kΩ, C_L = 15 pF(1)(2)	100-mV input step with 5-mV overdrive	1.3	µs
		TTL-level input step	0.3	

(1) C_L includes probe and jig capacitance.
(2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

7.12 Typical Characteristics

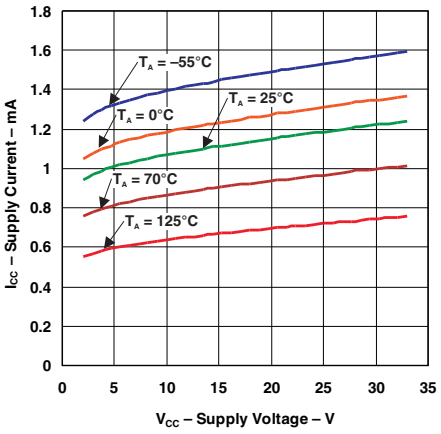


Figure 1. Supply Current vs Supply Voltage

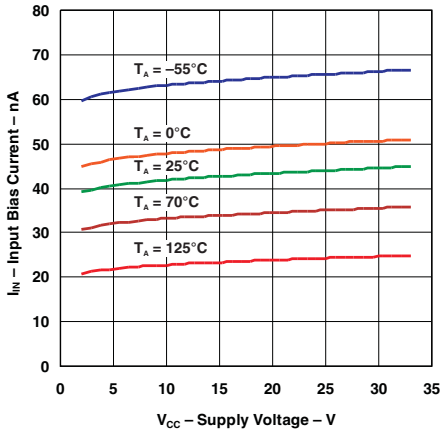


Figure 2. Input Bias Current vs Supply Voltage

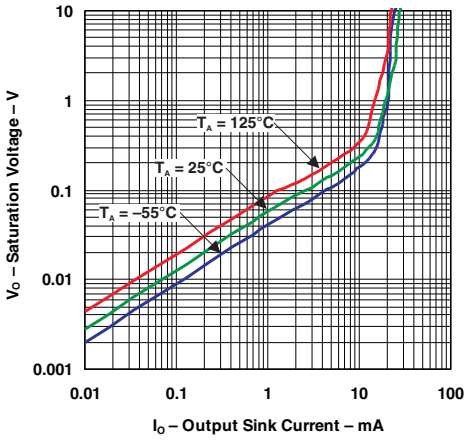


Figure 3. Output Saturation Voltage

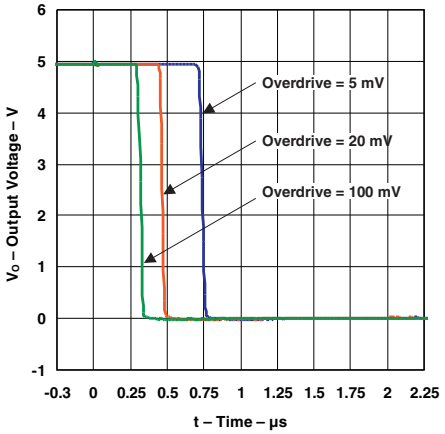


Figure 4. Response Time for Various Overdrives Negative Transition

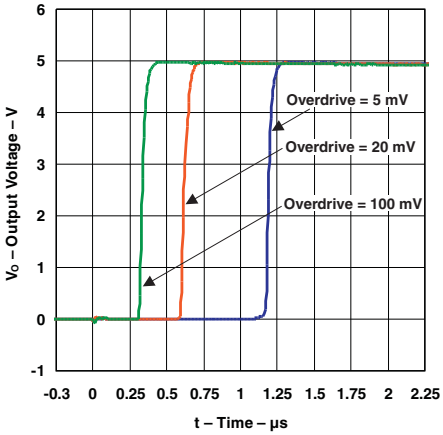


Figure 5. Response Time for Various Overdrives Positive Transition

8 Detailed Description

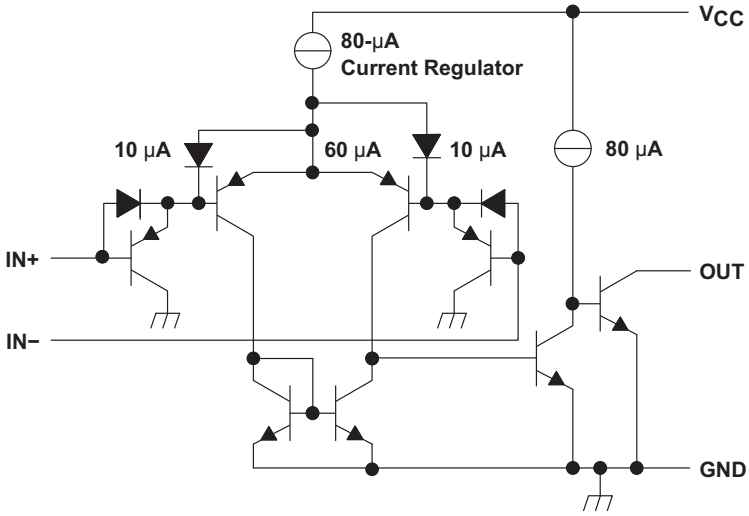
8.1 Overview

The LMx39 is a dual comparator with the ability to operate up to 36 V on the supply pin. This standard device has proven ubiquity and versatility across a wide range of applications. This is due to very wide supply voltages range (2 V to 36 V), low Iq, and fast response of the device.

This device is Q100 qualified and can operate over a wide temperature range (–40°C to 125°C).

The open-drain output allows the user to configure the output logic low voltage (V_{OL}) and allows the comparator to be used in AND functionality.

8.2 Functional Block Diagram



COMPONENT COUNT	
Epi-FET	1
Diodes	2
Resistors	2
Transistors	30

Figure 6. Schematic (Each Comparator)

8.3 Feature Description

LMx39 consists of a PNP Darlington pair input, allowing the device to operate with very high gain and fast response with minimal input bias current. The input Darlington pair creates a limit on the input common-mode voltage capability, allowing LMx39 to accurately function from ground to (V_{CC} – 1.5 V) differential input. This is enables much head room for modern day supplies of 3.3 V and 5 V.

The output consists of an open-drain NPN (pulldown or low-side) transistor. The output NPN sinks current when the positive input voltage is higher than the negative input voltage and the offset voltage. The VOL is resistive and scales with the output current. See the *Specifications* section for V_{OL} values with respect to the output current.

8.4 Device Functional Modes

8.4.1 Voltage Comparison

The LMx39 operates solely as a voltage comparator, comparing the differential voltage between the positive and negative pins and outputting a logic low or high impedance (logic high with pullup) based on the input differential polarity.

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Validate and test the design implementation to confirm system functionality.

9.1 Application Information

Typically, the LMx39 compares either a single signal to a reference or two signals. Many users take advantage of the open-drain output to drive the comparison logic output to a logic voltage level to an MCU or logic device. The wide supply range and high voltage capability makes LMx39 optimal for level shifting to a higher or lower voltage.

9.2 Typical Application

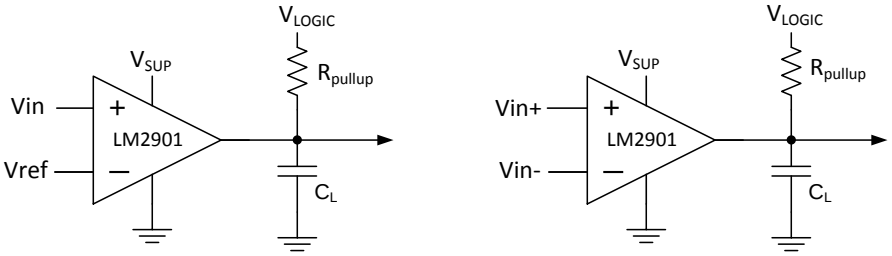


Figure 7. Single-ended and Differential Comparator Configurations

9.2.1 Design Requirements

For this design example, use the parameters listed in Table 1 as the input parameters.

Table 1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input Voltage Range	0 V to Vsup-1.5 V
Supply Voltage	2 V to 36 V
Logic Supply Voltage	2 V to 36 V
Output Current (R_{PULLUP})	1 µA to 20 mA
Input Overdrive Voltage	100 mV
Reference Voltage	2.5 V
Load Capacitance (C_L)	15 pF

9.2.2 Detailed Design Procedure

When using LMx39 in a general comparator application, determine the following:

- Input voltage range
- Minimum overdrive voltage
- Output and drive current
- Response time

9.2.2.1 Input Voltage Range

When choosing the input voltage range, the input common-mode voltage range (V_{ICR}) must be taken in to account. If temperature operation is above or below 25°C the V_{ICR} can range from 0 V to V_{CC}– 2 V. This limits the input voltage range to as high as V_{CC}– 2 V and as low as 0 V. Operation outside of this range can yield incorrect comparisons.

The following list describes the outcomes of some input voltage situations.

- When both IN– and IN+ are both within the common-mode range:
  - If IN– is higher than IN+ and the offset voltage, the output is low and the output transistor is sinking current
  - If IN– is lower than IN+ and the offset voltage, the output is high impedance and the output transistor is not conducting
- When IN– is higher than common mode and IN+ is within common mode, the output is low and the output transistor is sinking current
- When IN+ is higher than common mode and IN– is within common mode, the output is high impedance and the output transistor is not conducting
- When IN– and IN+ are both higher than common mode, the output is low and the output transistor is sinking current

9.2.2.2 Minimum Overdrive Voltage

Overdrive voltage is the differential voltage produced between the positive and negative inputs of the comparator over the offset voltage (V_{IO}). In order to make an accurate comparison, the overdrive voltage (V_{OD}) must be higher than the input offset voltage (V_{IO}). Overdrive voltage can also determine the response time of the comparator, with the response time decreasing with increasing overdrive. Figure 8 and Figure 9 show positive and negative response times with respect to overdrive voltage.

9.2.2.3 Output and Drive Current

Output current is determined by the load and pullup resistance and logic and pullup voltage. The output current produces a low-level output voltage (V_{OL}) from the comparator, where V_{OL} is proportional to the output current.

The output current can also effect the transient response.

9.2.2.4 Response Time

The load capacitance (C_L), pullup resistance (R_{PULLUP}), and equivalent collector-emitter resistance (R_{CE}) levels determine the transient response. Equation 1 approximates the positive response time. Equation 2 approximates the negative response time. Equation 3 calculates the collector-emitter resistance.

$$\tau_P \cong R_{PULLUP} \times C_L \quad (1)$$

$$\tau_N \cong R_{CE} \times C_L \quad (2)$$

$$R_{CE} = \frac{V_{OL}}{I_{OUT}} \quad (3)$$

where

- V_{OL} is the low-level output voltage
- I_{OUT} is the output current

9.2.3 Application Curves

Figure 8 and Figure 9 were generated with scope probe parasitic capacitance of 50 pF.

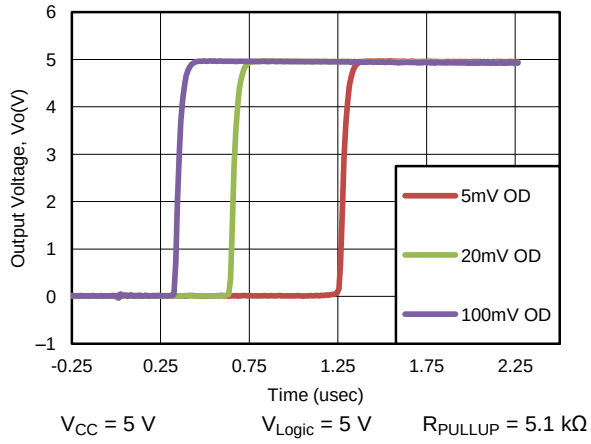


Figure 8. Response Time vs Output Voltage (Positive Transition)

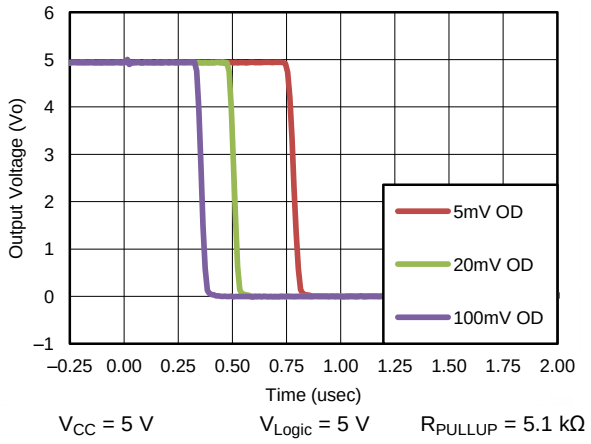


Figure 9. Response Time vs Output Voltage (Negative Transition)

10 Power Supply Recommendations

For fast response and comparison applications with noisy or AC inputs, use a bypass capacitor on the supply pin to reject any variation on the supply voltage. This variation can affect the common-mode range of the comparator input and create an inaccurate comparison.

11 Layout

11.1 Layout Guidelines

To create an accurate comparator application without hysteresis, maintain a stable power supply with minimized noise and glitches, which can affect the high level input common-mode voltage range. To achieve this accuracy, add a bypass capacitor between the supply voltage and ground. Place a bypass capacitor on the positive power supply and negative supply (if available).

NOTE

If a negative supply is not being used, do not place a capacitor between the GND pin of the device and system ground.

11.2 Layout Example

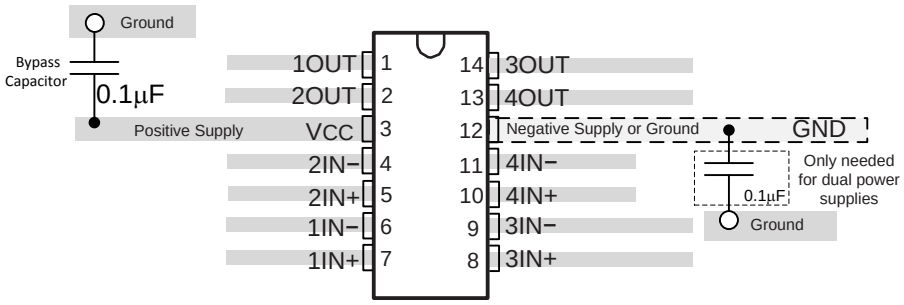


Figure 10. LMx39 Layout Example

12 Device and Documentation Support

12.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 2. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
LM139	Click here	Click here	Click here	Click here	Click here
LM239	Click here	Click here	Click here	Click here	Click here
LM339	Click here	Click here	Click here	Click here	Click here
LM139A	Click here	Click here	Click here	Click here	Click here
LM239A	Click here	Click here	Click here	Click here	Click here
LM339A	Click here	Click here	Click here	Click here	Click here
LM2901	Click here	Click here	Click here	Click here	Click here
LM2901AV	Click here	Click here	Click here	Click here	Click here
LM2901V	Click here	Click here	Click here	Click here	Click here

12.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.3 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

12.4 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.5 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-7700801VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-7700801VC A LM139JQMLV	Samples
5962-9673802V9B	ACTIVE	XCEPT	KGD	0	100	TBD	Call TI	N / A for Pkg Type	-55 to 125		Samples
5962-9673802VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9673802VC A LM139AJQMLV	Samples
LM139AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139A	Samples
LM139ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139A	Samples
LM139ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139A	Samples
LM139ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139A	Samples
LM139D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139	Samples
LM139DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139	Samples
LM139DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139	Samples
LM139DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139	Samples
LM239AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples
LM239ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples
LM239ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples
LM239ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples
LM239ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM239ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples
LM239D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239DRG3	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU | CU SN	N / A for Pkg Type	-25 to 85	LM239N	Samples
LM239NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-25 to 85	LM239N	Samples
LM239PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	L239	Samples
LM239PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	L239	Samples
LM239PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-25 to 85	L239	Samples
LM239PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	L239	Samples
LM239PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	L239	Samples
LM2901AVQDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901AV	Samples
LM2901AVQDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901AV	Samples
LM2901AVQPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901AV	Samples
LM2901AVQPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901AV	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM2901D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DRG3	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	LM2901N	Samples
LM2901NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	LM2901N	Samples
LM2901NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901	Samples
LM2901PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901	Samples
LM2901PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-40 to 125	L2901	Samples
LM2901PWRG3	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	L2901	Samples
LM2901PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901	Samples
LM2901VQDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901V	Samples
LM2901VQDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901V	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM2901VQPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901V	Samples
LM2901VQPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901V	Samples
LM339AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU | CU SN	N / A for Pkg Type	0 to 70	LM339AN	Samples
LM339ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM339AN	Samples
LM339ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM339APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DRG3	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU | CU SN	N / A for Pkg Type	0 to 70	LM339N	Samples
LM339NE3	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	LM339N	Samples
LM339NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM339N	Samples
LM339NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339	Samples
LM339PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339	Samples
LM339PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	0 to 70	L339	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM339PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339	Samples
LM339PWRG3	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	L339	Samples
LM339PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF LM139, LM139-SP, LM239A, LM2901, LM2901AV, LM2901V :

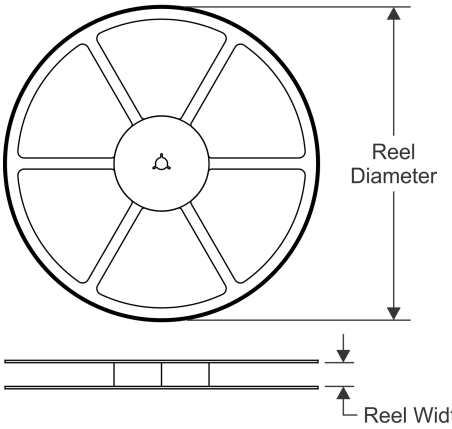
- Catalog: LM139
- Automotive: LM239A-Q1, LM2901-Q1, LM2901AV-Q1, LM2901V-Q1
- Enhanced Product: LM239A-EP
- Space: LM139-SP

NOTE: Qualified Version Definitions:

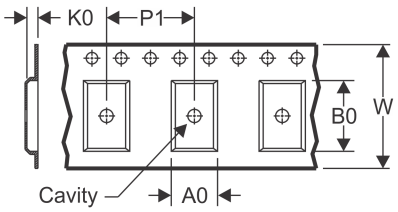
- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

REEL DIMENSIONS

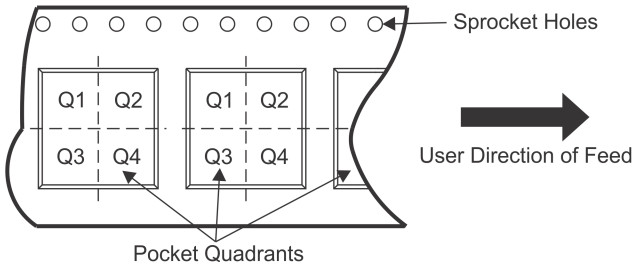


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

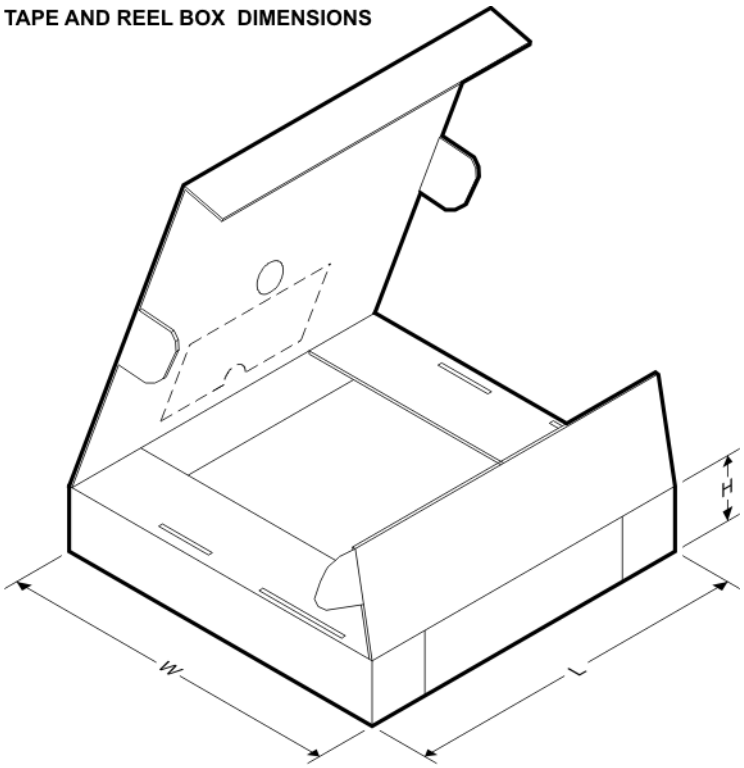


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM139ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM139DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239ADR	SOIC	D	14	2500	330.0	17.0	6.4	9.05	2.1	8.0	16.0	Q1
LM239ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM239DR	SOIC	D	14	2500	330.0	17.0	6.4	9.05	2.1	8.0	16.0	Q1
LM239DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239DRG3	SOIC	D	14	2500	330.0	17.0	6.4	9.05	2.1	8.0	16.0	Q1
LM239DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM239DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM239PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM239PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901AVQPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901AVQPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901DR	SOIC	D	14	2500	330.0	17.0	6.4	9.05	2.1	8.0	16.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2901DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM2901DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2901DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2901DRG3	SOIC	D	14	2500	330.0	17.0	6.4	9.05	2.1	8.0	16.0	Q1
LM2901DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM2901DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2901NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM2901PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901PWRG3	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901VQPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901VQPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM339ADR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM339ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339ADR	SOIC	D	14	2500	330.0	17.0	6.4	9.05	2.1	8.0	16.0	Q1
LM339ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339ADRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM339APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339APWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM339DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM339DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM339DRG3	SOIC	D	14	2500	330.0	17.0	6.4	9.05	2.1	8.0	16.0	Q1
LM339DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339PWRG3	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

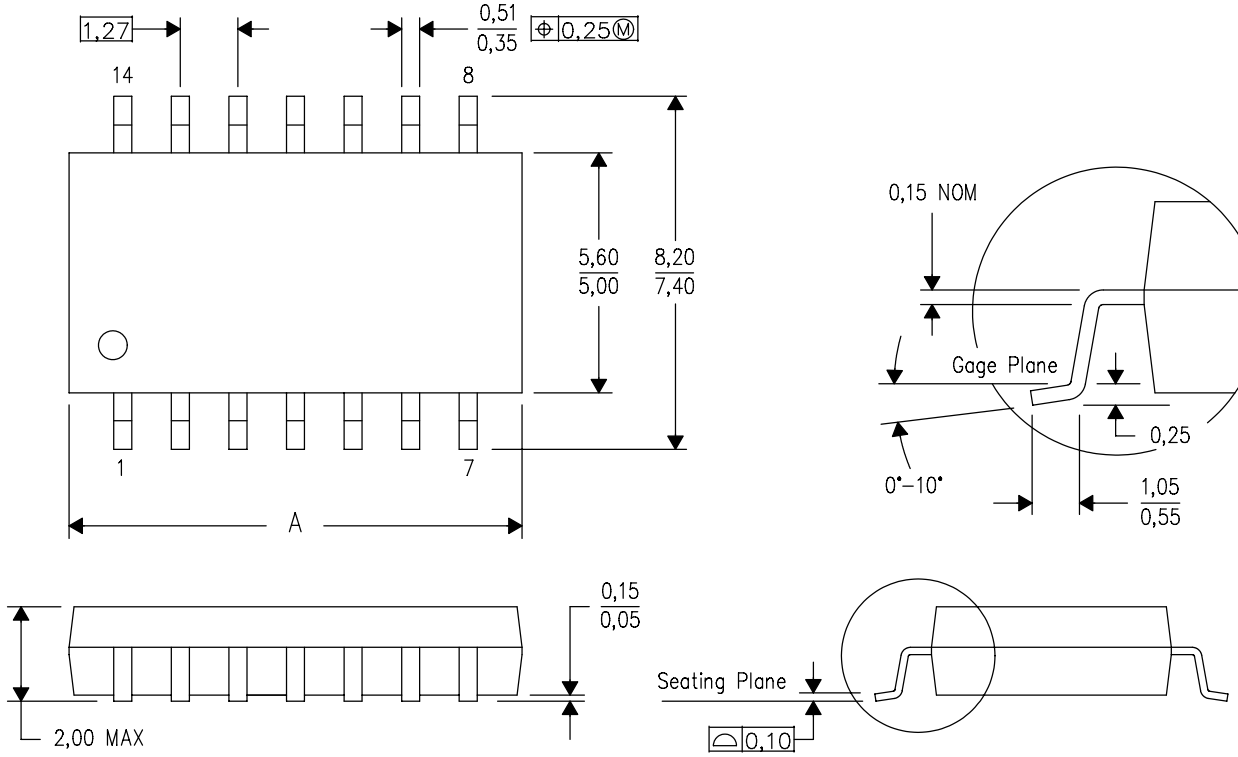
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM139ADR	SOIC	D	14	2500	367.0	367.0	38.0
LM139DR	SOIC	D	14	2500	367.0	367.0	38.0
LM239ADR	SOIC	D	14	2500	333.2	345.9	28.6
LM239ADR	SOIC	D	14	2500	333.2	345.9	28.6
LM239ADR	SOIC	D	14	2500	367.0	367.0	38.0
LM239DR	SOIC	D	14	2500	364.0	364.0	27.0
LM239DR	SOIC	D	14	2500	333.2	345.9	28.6
LM239DR	SOIC	D	14	2500	367.0	367.0	38.0
LM239DR	SOIC	D	14	2500	333.2	345.9	28.6
LM239DRG3	SOIC	D	14	2500	333.2	345.9	28.6
LM239DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM239DRG4	SOIC	D	14	2500	333.2	345.9	28.6
LM239PWR	TSSOP	PW	14	2000	364.0	364.0	27.0
LM239PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM239PWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2901AVQPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2901AVQPWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2901DR	SOIC	D	14	2500	333.2	345.9	28.6
LM2901DR	SOIC	D	14	2500	364.0	364.0	27.0
LM2901DR	SOIC	D	14	2500	367.0	367.0	38.0

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2901DR	SOIC	D	14	2500	333.2	345.9	28.6
LM2901DRG3	SOIC	D	14	2500	333.2	345.9	28.6
LM2901DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM2901DRG4	SOIC	D	14	2500	333.2	345.9	28.6
LM2901NSR	SO	NS	14	2000	367.0	367.0	38.0
LM2901PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2901PWR	TSSOP	PW	14	2000	364.0	364.0	27.0
LM2901PWRG3	TSSOP	PW	14	2000	364.0	364.0	27.0
LM2901PWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2901VQPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2901VQPWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM339ADBR	SSOP	DB	14	2000	367.0	367.0	38.0
LM339ADR	SOIC	D	14	2500	364.0	364.0	27.0
LM339ADR	SOIC	D	14	2500	367.0	367.0	38.0
LM339ADR	SOIC	D	14	2500	333.2	345.9	28.6
LM339ADR	SOIC	D	14	2500	333.2	345.9	28.6
LM339ADRG4	SOIC	D	14	2500	333.2	345.9	28.6
LM339ANSR	SO	NS	14	2000	367.0	367.0	38.0
LM339APWR	TSSOP	PW	14	2000	364.0	364.0	27.0
LM339APWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM339APWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM339DBR	SSOP	DB	14	2000	367.0	367.0	38.0
LM339DR	SOIC	D	14	2500	333.2	345.9	28.6
LM339DR	SOIC	D	14	2500	364.0	364.0	27.0
LM339DR	SOIC	D	14	2500	367.0	367.0	38.0
LM339DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM339DRG3	SOIC	D	14	2500	333.2	345.9	28.6
LM339DRG4	SOIC	D	14	2500	333.2	345.9	28.6
LM339PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM339PWR	TSSOP	PW	14	2000	364.0	364.0	27.0
LM339PWRG3	TSSOP	PW	14	2000	364.0	364.0	27.0
LM339PWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

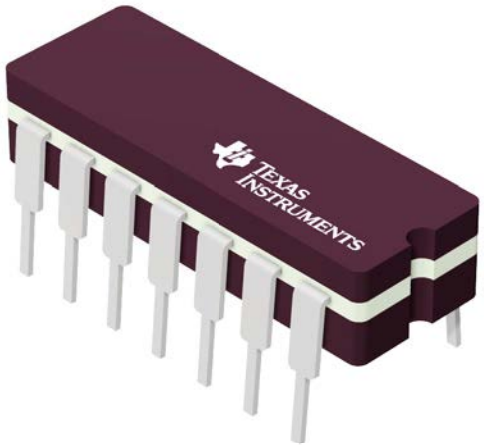
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

GENERIC PACKAGE VIEW

J 14 CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

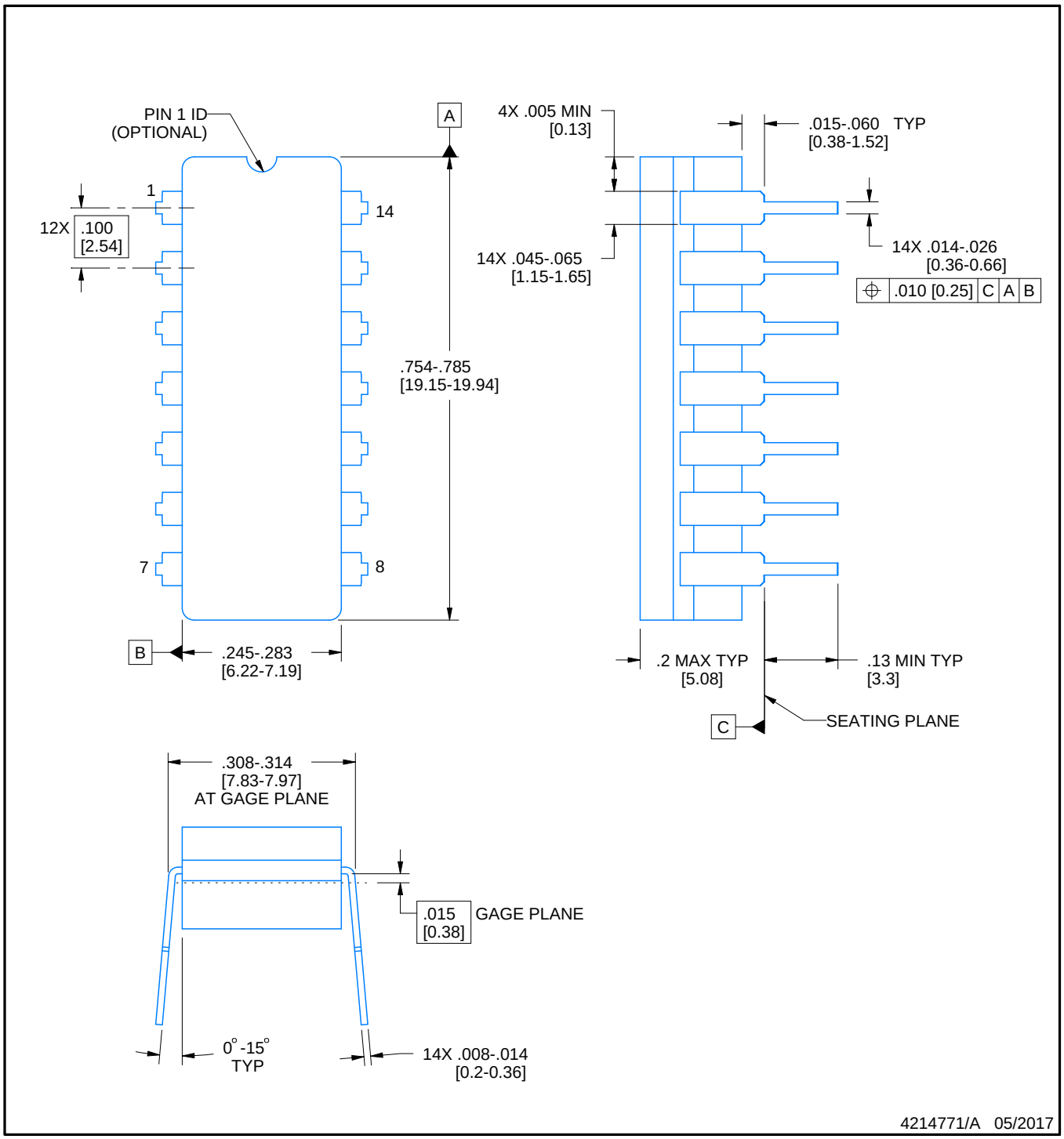
4040083-5/G

PACKAGE OUTLINE

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

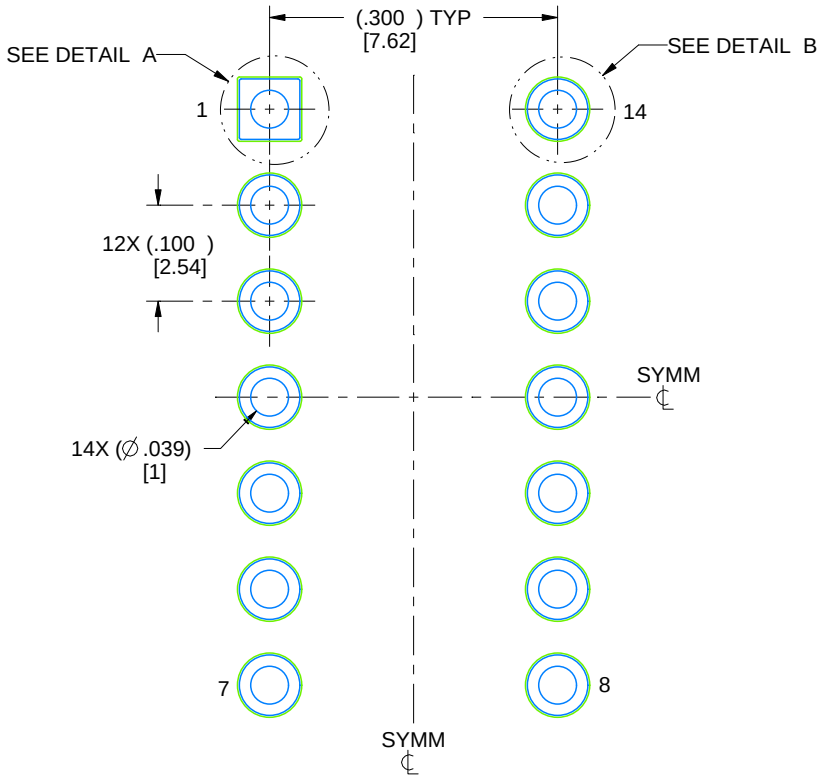
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

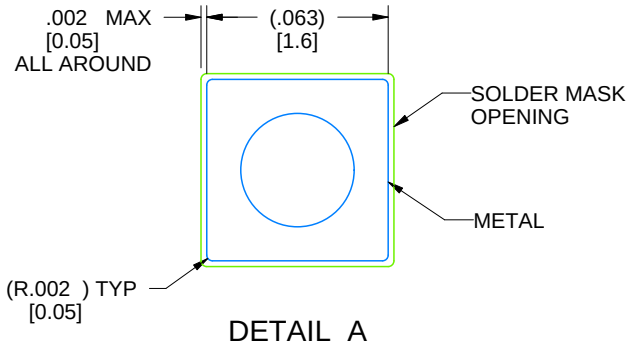
J0014A

CDIP - 5.08 mm max height

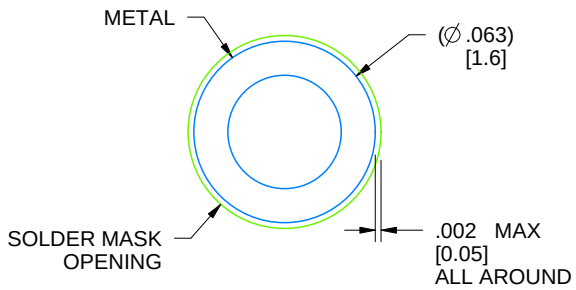
CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



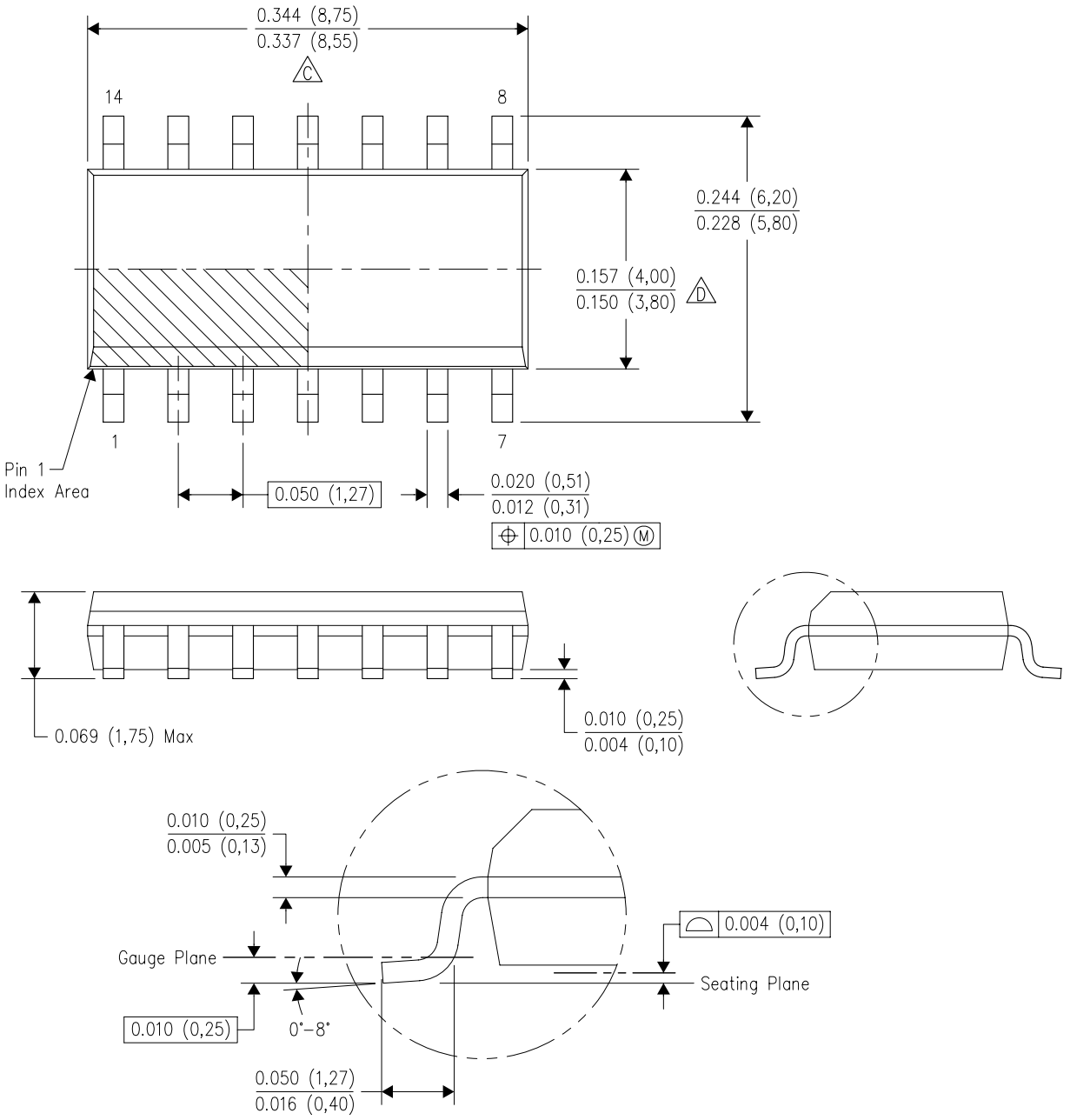
DETAIL A
SCALE: 15X



DETAIL B
13X, SCALE: 15X

4214771/A 05/2017

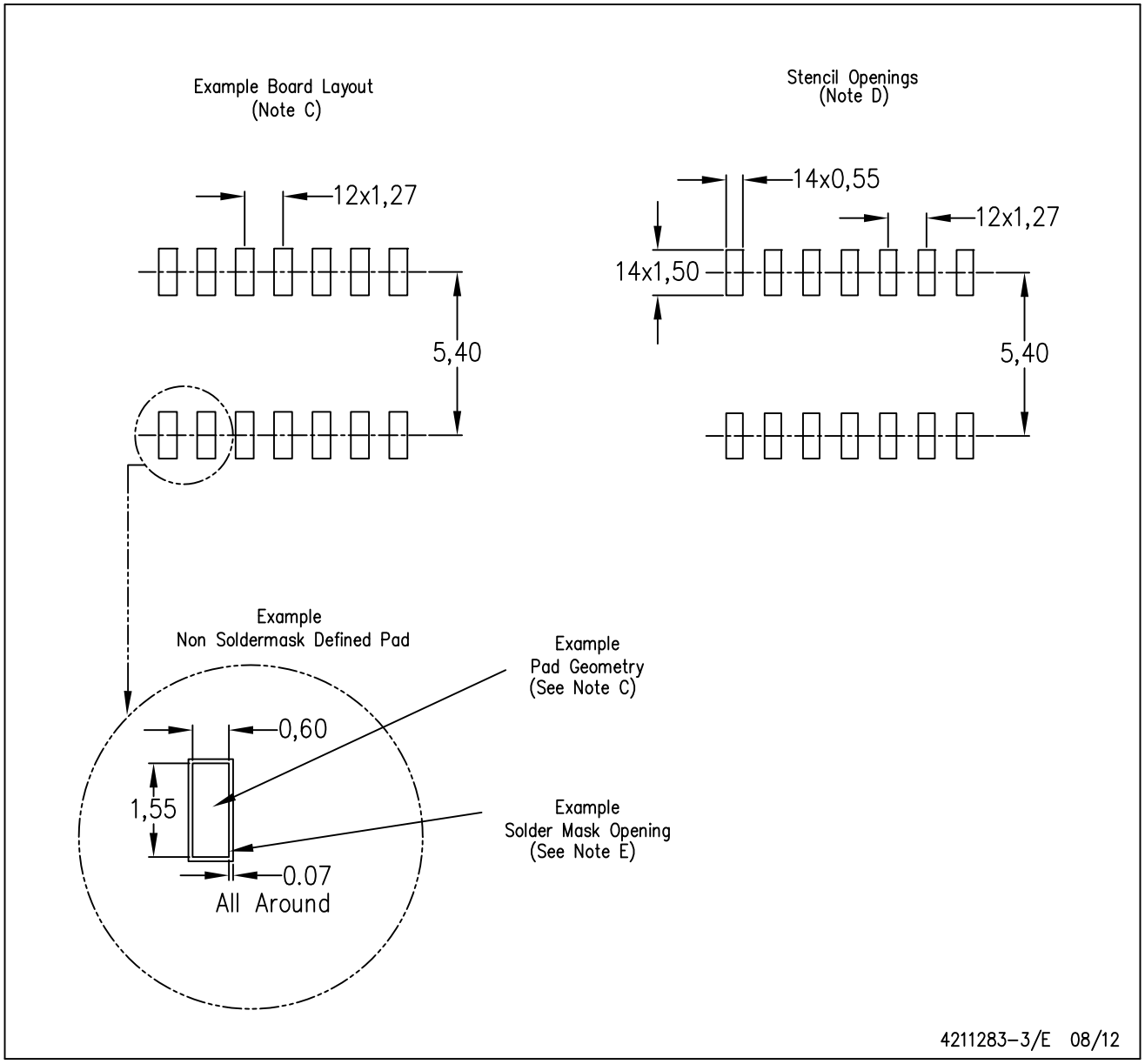
D (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040047–5/M 06/11

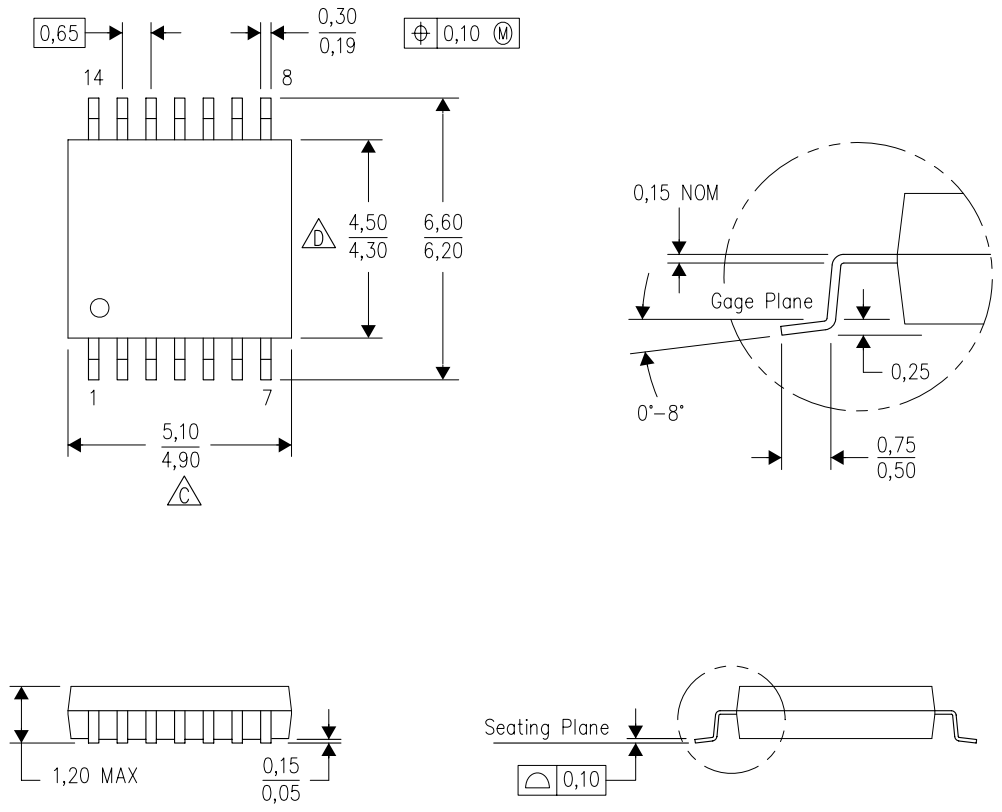
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

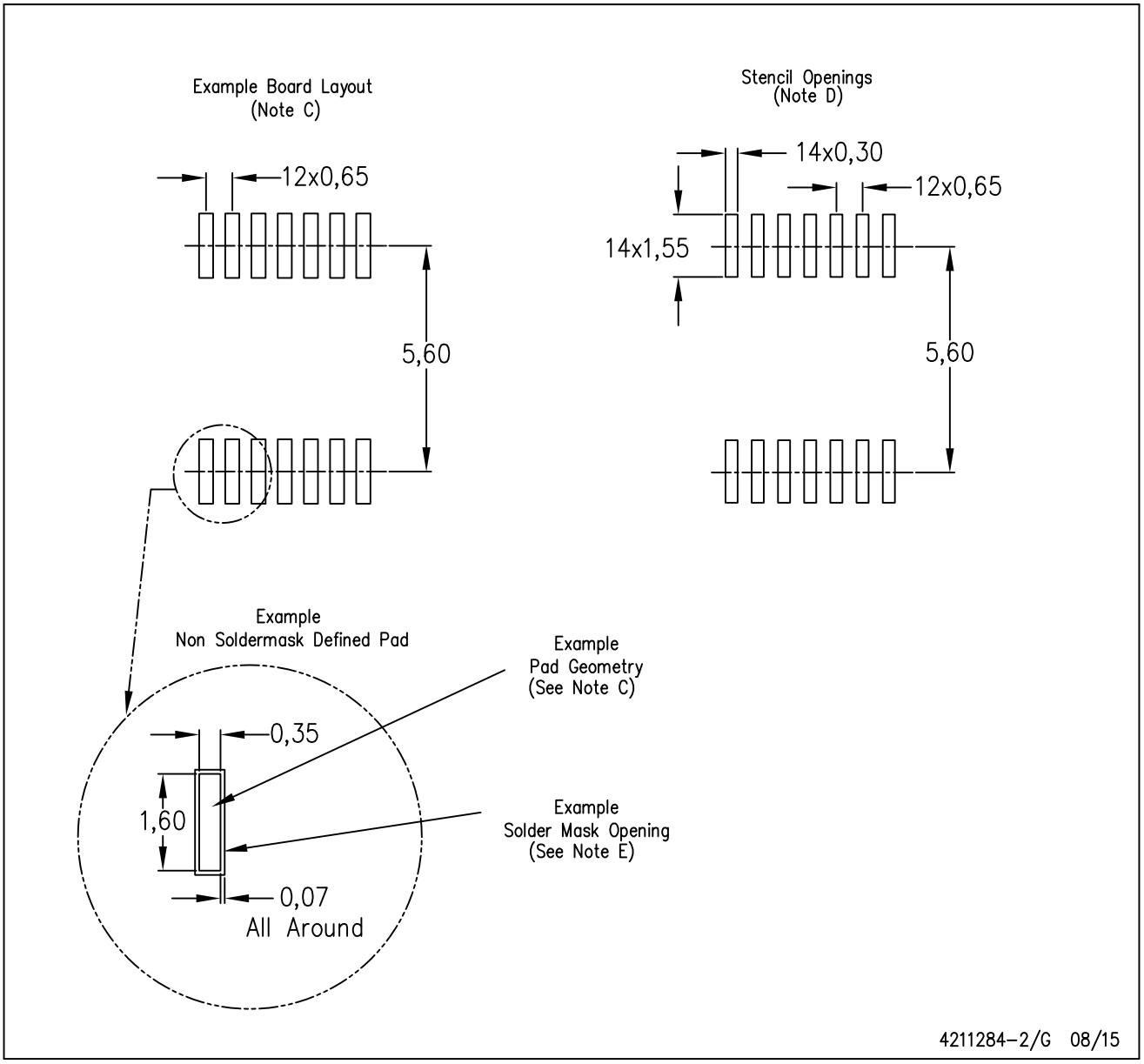
PW (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040064–3/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G14) PLASTIC SMALL OUTLINE

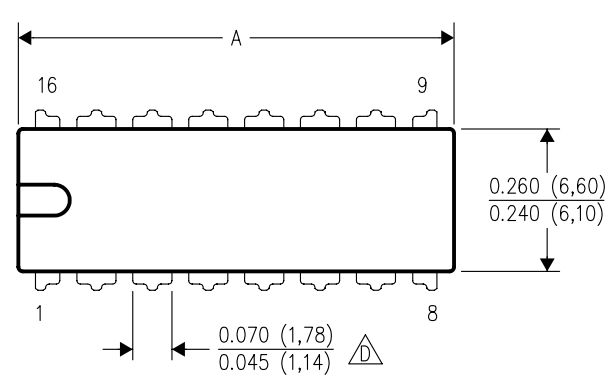


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

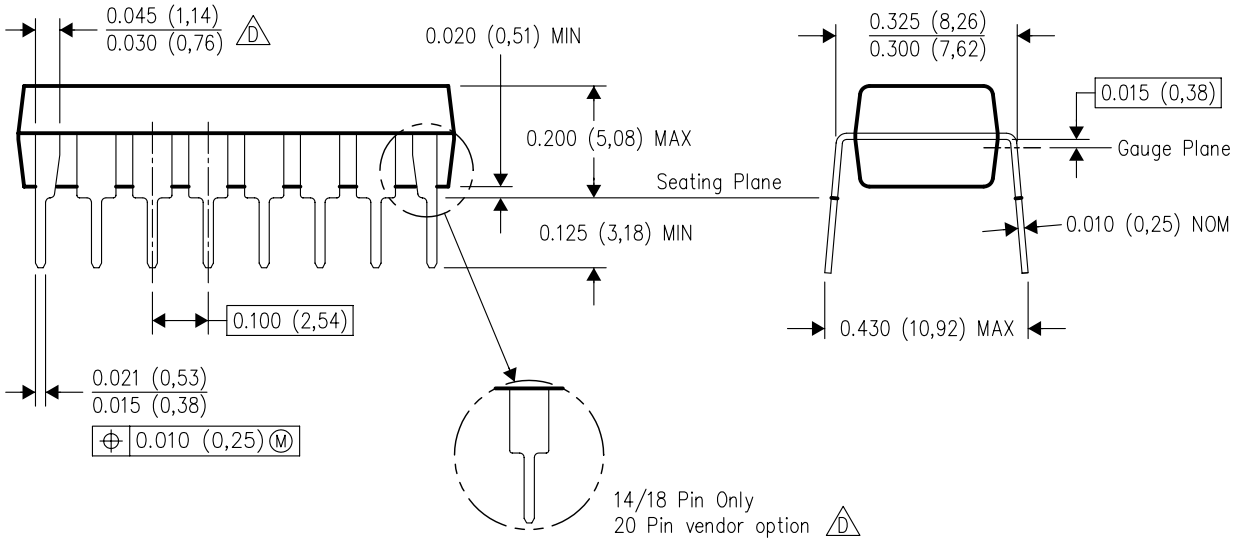
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



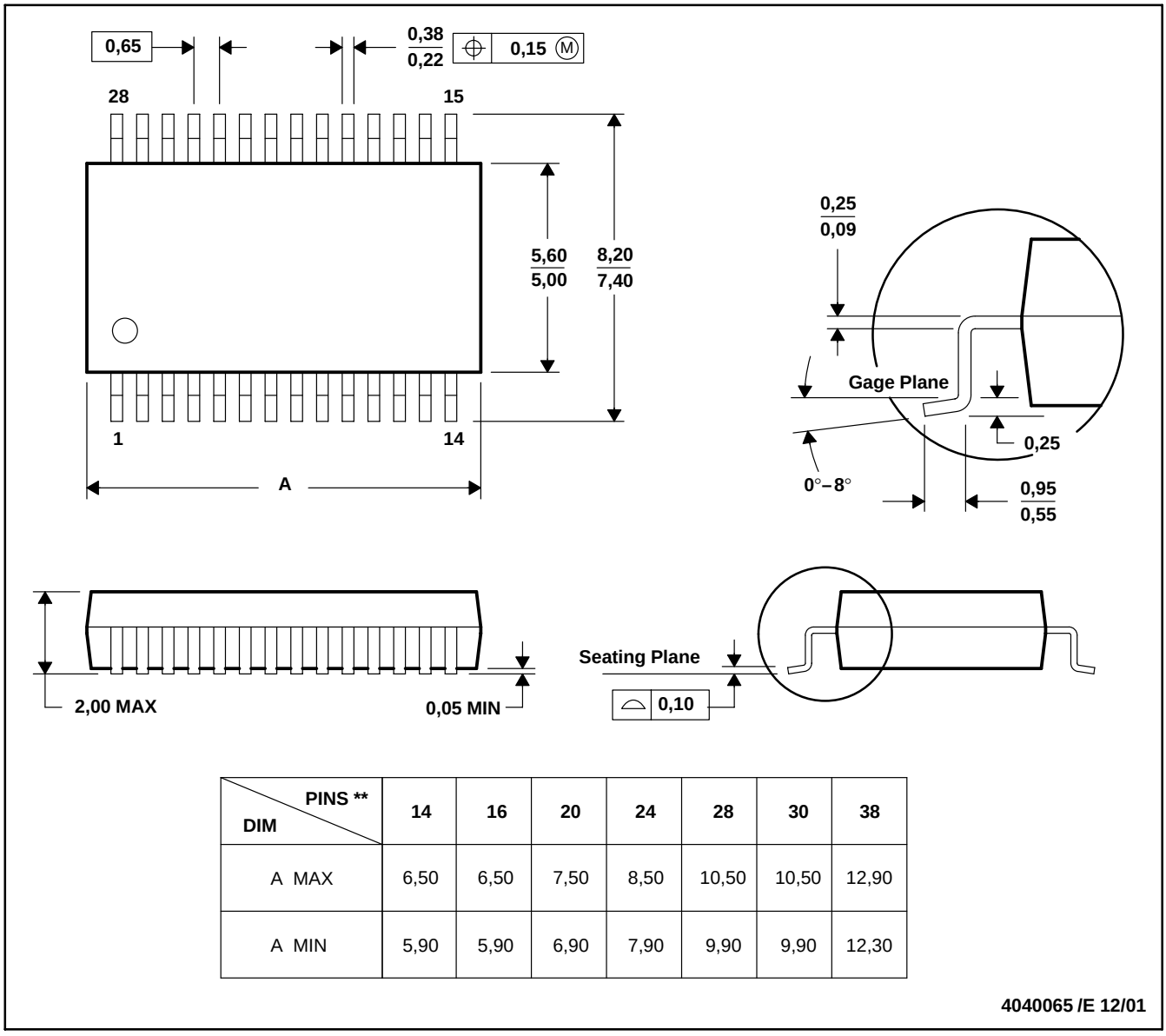
4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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